Hamatech Hot SC1/SC2

Manager: Edward Camacho
Backup: Garry Bordonaro

Safety
- Stay away from chamber top during process
- Do not reach into chamber top during process
- Strong bases used in process
- Strong acids used in process

Process Restrictions
Material Restrictions
- Whole wafers or masks sized for available chucks only
- Check wafer for materials incompatible with cleaning chemistry to prevent substrate damage

Parameter Restrictions
- Existing programs only

Scheduling / Sign-up Restrictions
- None

Requirements (Do Every Time)
- Turn tool off after each use
- Use the correct sized chuck for your substrate
- Load substrate into chuck carefully and properly
- Report any alarms to staff

Prohibitions (Never Do)
- NEVER operate without proper training from staff
- NEVER operate while errors are present
- NEVER refill chemical containers
- NEVER put chemicals into chamber
- NEVER remove substrates if tool loses power mid-cycle

Common Problems

<table>
<thead>
<tr>
<th>Problem:</th>
<th>Root Cause:</th>
<th>Solution:</th>
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<tbody>
<tr>
<td>Tool beeping with an error msg.</td>
<td>Low chemical tanks</td>
<td>Contact staff to correct</td>
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<tr>
<td>Wafer falls off chuck</td>
<td>Wafer improperly placed in chuck</td>
<td>Review wafer loading instructions and try again</td>
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Other Comments or Cautions
- Contact staff if you break a wafer or mask in the chamber